

Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

A

A

B

B

C

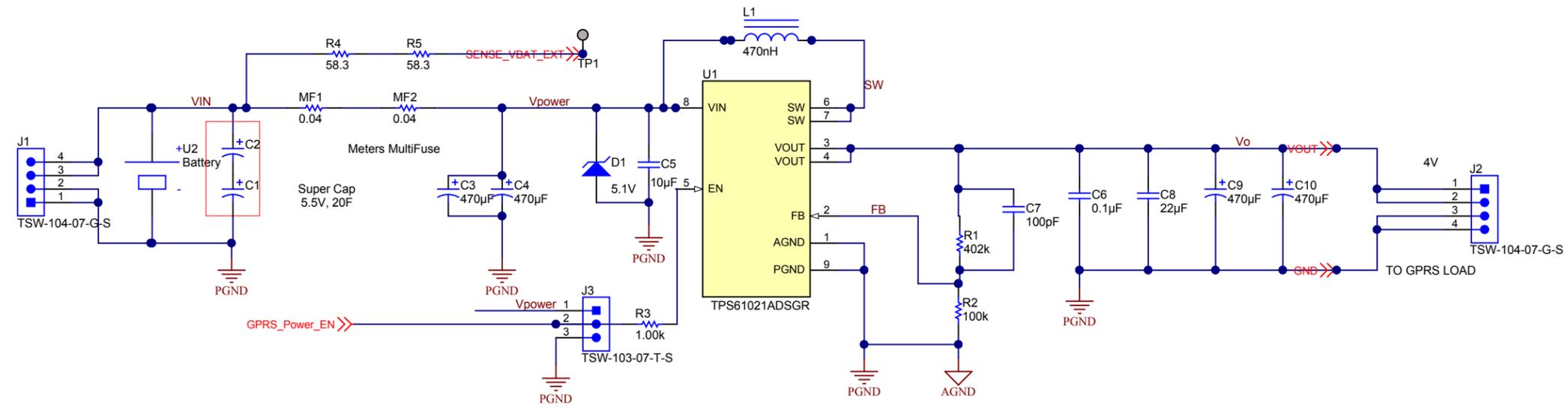
C

D

D

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Orderable: N/A	Designed for: Public Release	Mod. Date: 12/12/2016	 http://www.ti.com <small>© Texas Instruments 2016</small>
TID #: TIDA-01387	Project Title: Change in menu Project Project Options Parameters		
Number: TIDA-01387	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3	
Drawn By:	File: CoverSheet.SchDoc	Size: B	
Engineer: Enter name of project lead	Contact: http://www.ti.com/support		



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Orderable: N/A	Designed for: Public Release	Mod. Date: 1/13/2017	 TEXAS INSTRUMENTS http://www.ti.com
TID #: TIDA-01387	Project Title: Change in menu Project Project Options Parameters	Sheet: 2 of 3	
Number: TIDA-01387	Rev: E1	Sheet Title:	Size: B © Texas Instruments 2016
SVN Rev: Version control disabled	Assembly Variant: 001	File: BlankSheet.SchDoc	
Drawn By:	Engineer: Enter name of project lead	Contact: http://www.ti.com/support	

H1 NY PMS 440 0025 PH
 H2 NY PMS 440 0025 PH
 H3 NY PMS 440 0025 PH
 H4 NY PMS 440 0025 PH

H5 1902C
 H6 1902C
 H7 1902C
 H8 1902C

H9 SJ-5303 (CLEAR)
 H10 SJ-5303 (CLEAR)
 H11 SJ-5303 (CLEAR)
 H12 SJ-5303 (CLEAR)

DNP FID1
 DNP FID2
 DNP FID3

PCB Number: TIDA-01387
 PCB Rev: E1

PCB
 LOGO
 Pb-Free Symbol

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ2
Assembly Note
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TIDA-01387	Project Title: Change in menu Project Project Options Parameters		
Number: TIDA-01387	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By:	File: TID_Hardware.SchDoc	Size: B	
Engineer: Enter name of project lead	Contact: http://www.ti.com/support		

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